



DEVELOPMENT OF A SOLO SPECTROSCOPY GAS SENSOR IN THE MID-IR

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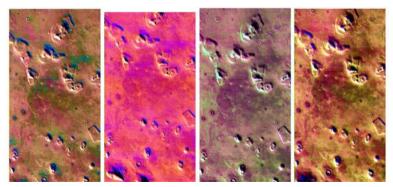
EMERGING TECHNOLOGIES WORKSHOP 3RD- 4TH MAY 2017



Space-based Spectroscopy

- Main spectroscopic analysis areas
 - Hyperspectral imaging of earth
 - Imaging of Amazon for deforestation
 - Imaging of ice caps
 - Military uses
 - Spectroscopy of the moon / Mars







Spectroscopy in Space

- Current and planned solutions are not ideal
 - Heavy payload
 - Most have moving parts
 - Do not span entire spectral range or do not have high resolution
 - Relatively high power consumption
 - Degree of temperature control
 - Lack of versatility / dynamic reconfiguration
 - Scan speed limits pixel size

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What is the problem we are trying to solve?

- Current spectrometers have multiple components
 - Alignment issues
 - Expensive to manufacture
 - Optical effects loss of photons / stray light
 - Miniaturisation difficult spectral resolution suffers as size of spectrometer is decreased



What if you could combine

The spectral resolving capability of a spectrometer...

With the size of

1

photodetector?

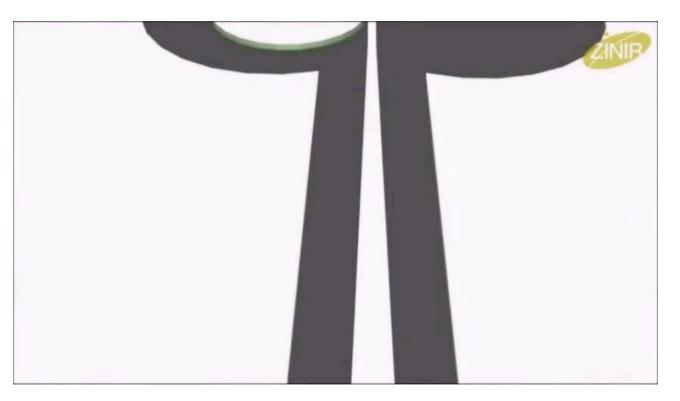
Background image credit: NASA

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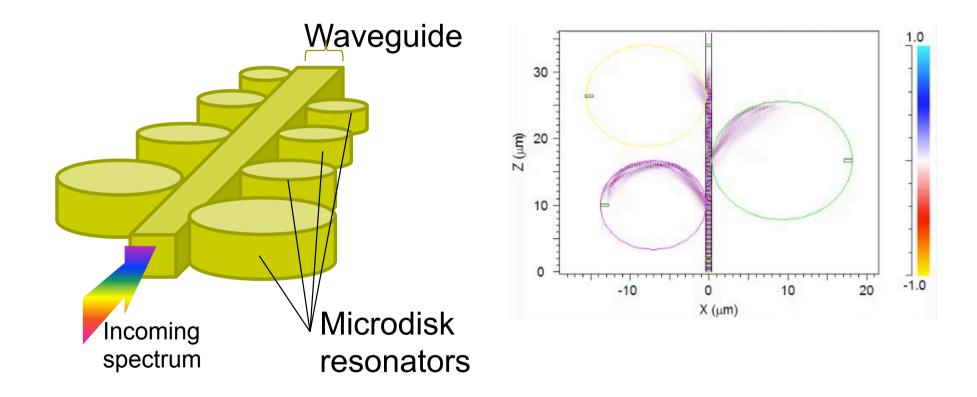
A monolithic chip-based spectrometer



Broadband light travels down the central waveguide

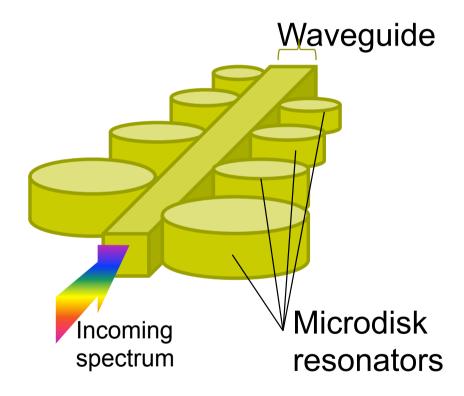
Differently sized microdisk resonators pick out specific wavelengths Each resonator is a separately addressable photodiode

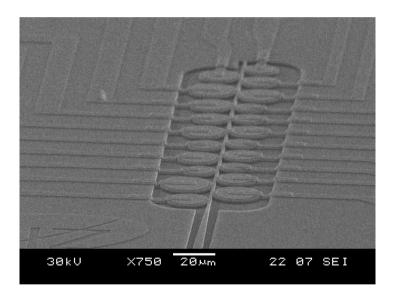






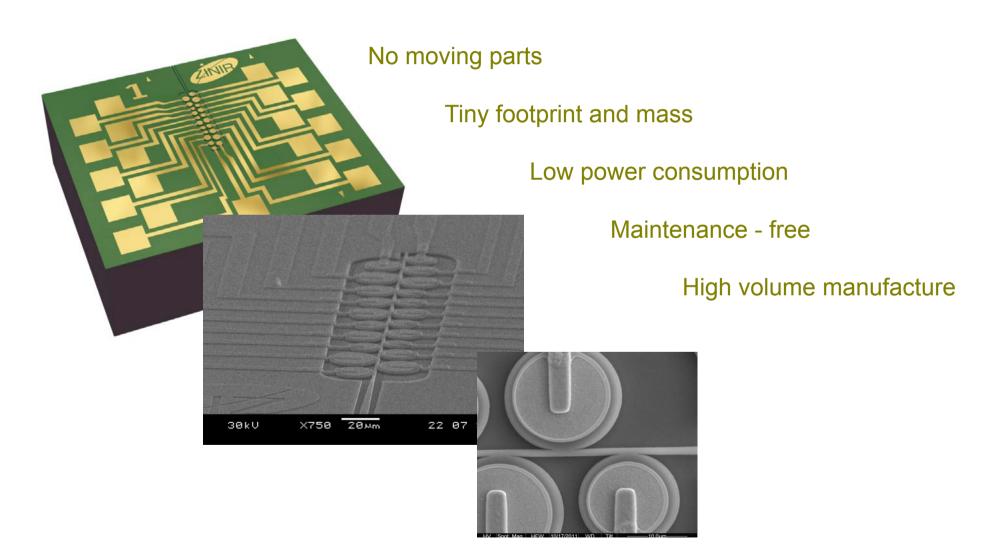
Our solution: Resonant Detector Array











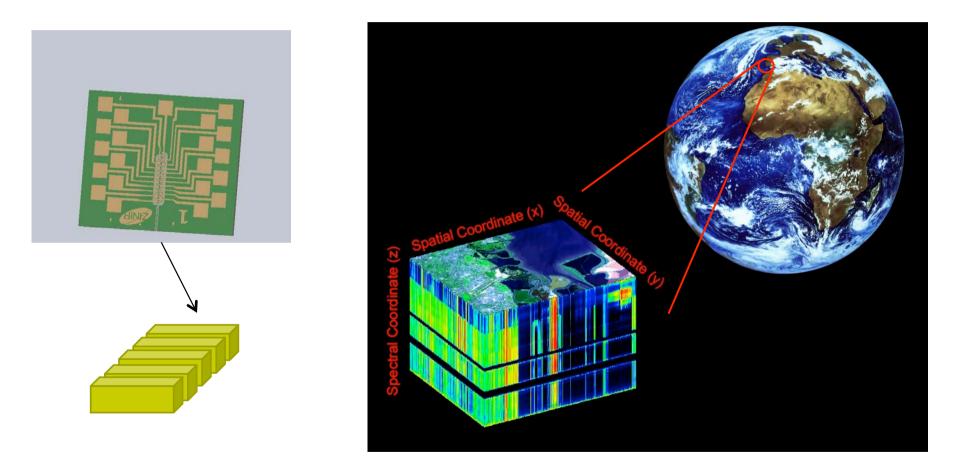


Different spectroscopy approaches

	Czerny Turner rotating grating	Grating and detector array	MEMS grating based	FTIR	Plasmon Filter based	Solo
Single component	×	×	×	×	×	\checkmark
High spectral resolution	\checkmark	\checkmark	×	\checkmark	×	\checkmark
Low mass (<500grams)	×	×	\checkmark	×	×	\checkmark
No moving parts	×	\checkmark	×	×	\checkmark	\checkmark
Low temperature sensitivity	×	×	×	×	×	\checkmark
Inexpensive manufacturing	×	×	×	×	\checkmark	\checkmark
Very small footprint (<10cm ³)	×	×	\checkmark	×	\checkmark	\checkmark
Spectral features adjustable by end user in real time	\checkmark	\checkmark	×	\checkmark	×	\checkmark



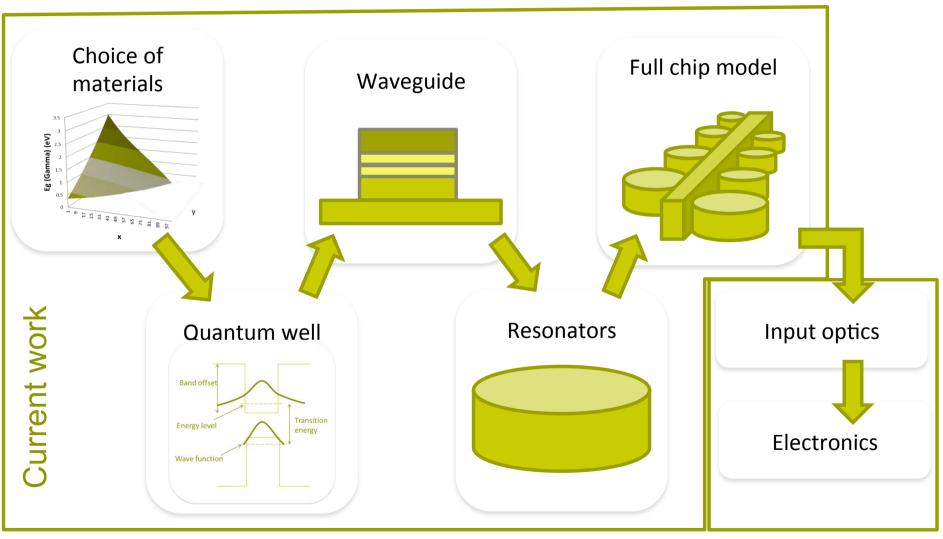
Arrays for hyperspectral imaging



Chip approach allows for relatively straightforward linear arrays



Design: Electronic and Optical Parameters



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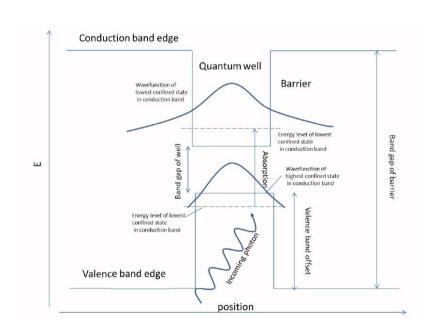
Approaches

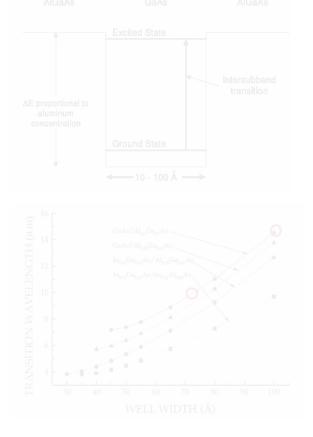
Shorter wavelengths

• Interband approach

Longer wavelengths

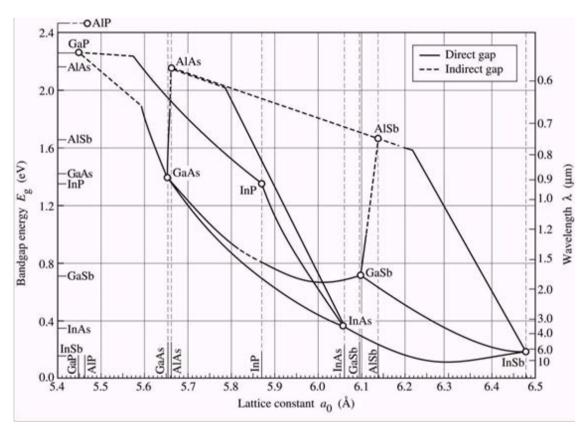
• Intraband approach







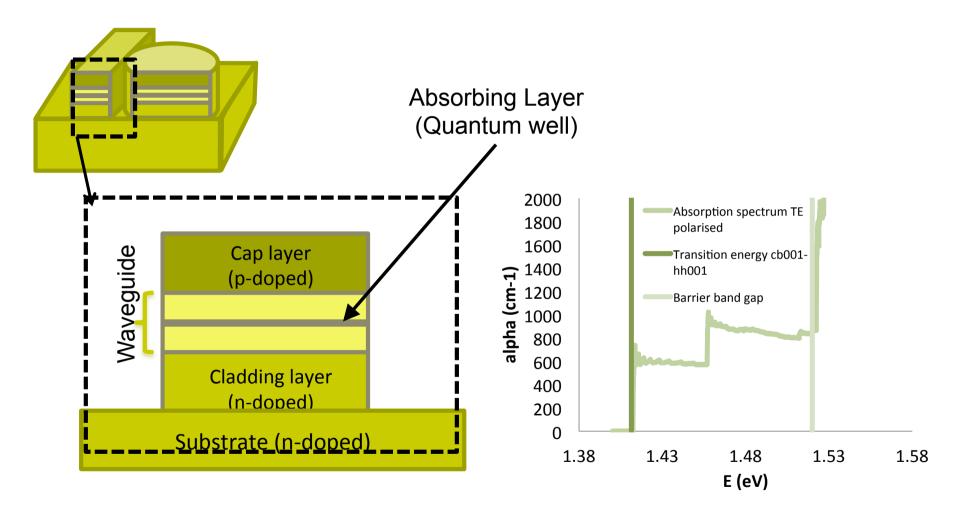
Interband devices – exploit range of III-V semiconductors



- InGaAs(P)/InP:
 - 1200-1700 nm range.
 - Direct band gap
 - Well-established material system commonly used in telecommunications device applications.
 - Applications in this range include gas sensing, e.g. CO₂.
- InGa(As)Sb/GaSb:
 - 2000-3000 nm range.
 - Direct band gap
 - Material used for mid-infrared lasers
 - Tolerances are more favourable due to the large feature size

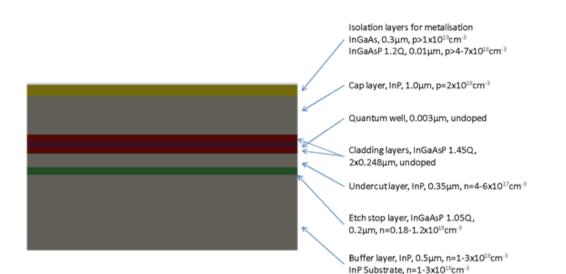


Layer structure: quantum well

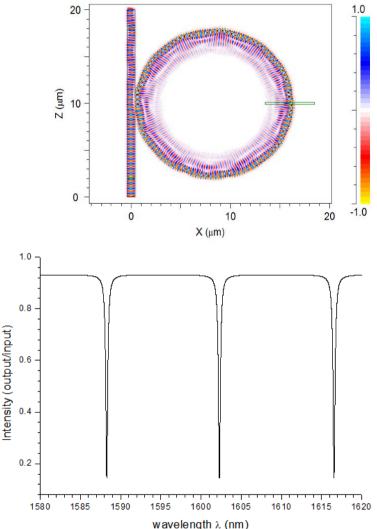




The 1600nm chip (interband)



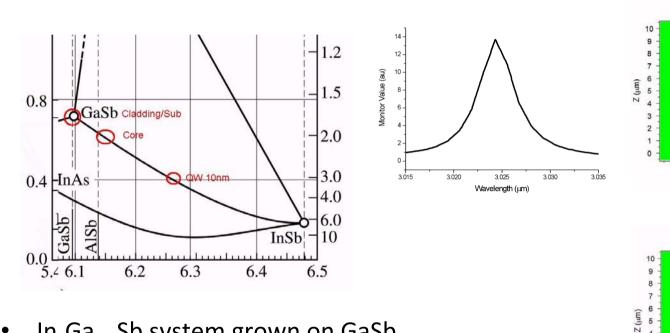
Contour Map of Ey



The InGaAsP/InP system provides a good solution for a system operating around 1600nm benefitting from mature telecomms device semiconductors



Extending to longer wavelengths (λ =3µm chip (interband)



- In_xGa_{1-x}Sb system grown on GaSb
- 10nm thick QW •
- 3um disk radius •
- Strong resonance observed close • to 3um with linewidth of 4.6nm

-10

-1.0

Contour Map of Ey

X (µm)

Contour Map of Ey

On resonance

-2

.2

0

6 8

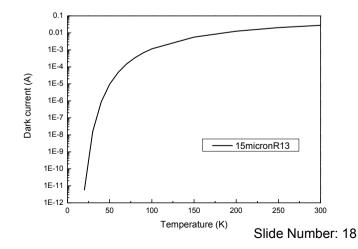
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Off resonance



Issues going to even longer wavelengths

- Interested in feasibility of using Solo concept out to 15.0µm
- Issues:
 - Non-radiative carrier recombination increases as wavelength increases (Auger processes)
 - Difficulty of obtaining high quality material (leads to defect-related recombination)
 - Cost/availability of materials
 - Thermal noise / dark current





Approaches

Shorter wavelengths

Interband approach

Longer wavelengths

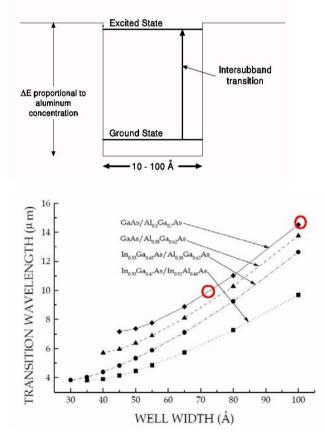
AlGaAs

• Intraband approach

GaAs

AlGaAs

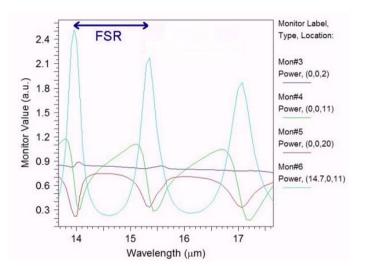




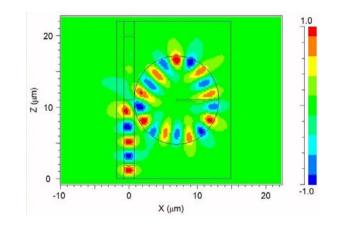
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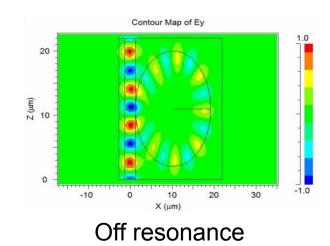
Exploiting quantum confinement control for long wavelength operation15µm chip (intraband)



- 25 x GaAs 10.8 nm QWs separated by 50 nm AlGaAs barriers
- Disk radius 6µm
- Resonant linewidth of 300 nm
- Large FSR of 1400 nm

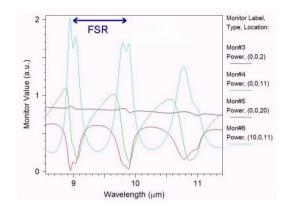


On resonance

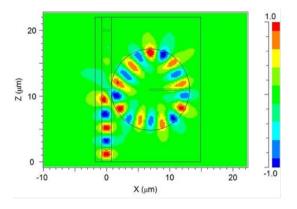




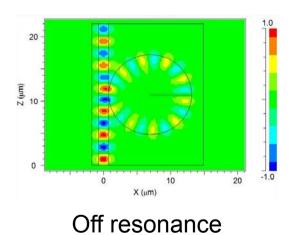
10µm design (intraband)



- A waveguide structure containing 25x GaAs 7.35 nm QWs separated by 50 nm AlGaAs barriers
- Disk radius 6µm
- Resonant linewidth of 206 nm
- FSR of 900 nm
- Initial characteristics look promising



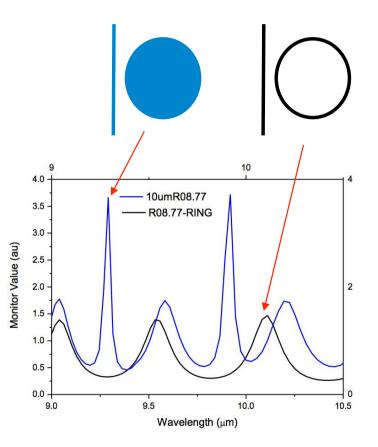
On resonance





Removal of parasitic modes: ring and other geometries

- Preliminary investigation of disk versus ring geometry.
- The ring provides a method of mode exclusion, to be explored in future work together with other geometries



Summary

- Solo spectrometer approach offers a monolithic solution for spectroscopy in the optical domain
- The approach may be applied across a broad wavelength range through choice of an appropriate semiconductor alloy (up to 3000nm in principle)
- The use of an intraband approach extends the operating window significantly with 15um achievable with a GaAs/AlGaAs system
- Future work will focus on detailed device design and prototype manufacture





Sensitivity – signal current

Target Wavelength (μm)	Responsivity (A/W)
1.6	
3.0	7.70
5.0	5.23
10.0	12.65
15.0	11.63

Calculated resonator responsivities assuming 100% IQE and all absorbed power leads to carrier generation

We specialise in **Photonics technology** With expertise in **III-V and silicon semiconductor devices** Optical design Semiconductor modelling Solid state spectrometers **Integrated optics** Remote sensing Photonics design and simulation **Biosensors** Light sources Optical sensors Detectors Medical imaging Technology transfer Commercialisation Market analysis Project management Patents and IP **Funding bids** Roadmapping